

技术数据表

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UV8110-PO10WF

UV减粘膜

简介

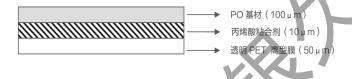
UV8110-P010WF是一款使用层110 μ m 厚、P0为基材,涂以丙烯酸粘合剂制成的UV减粘保护膜。

产品特性

UV照射前粘性极高,UV照射后粘性急剧降低,可轻易地无痕剥离; 使用过程中不残胶、无污染; UV前持粘性能优,良好的保护固定作用;

产品结构

UV 减粘膜主要由离型膜、丙烯酸粘合剂、基材三部分组成。



产品应用

适用于半导体行业电子元器件、晶圆 (wafer)、玻璃、陶瓷、镜头、芯片定位 制程保护。

封装领域:各种封装件(QFN/BGA/DFN)的切割用;晶圆研磨、切割用。

光学领域:各种镀膜玻璃、普通玻璃的 开槽、切割、酸洗用。

其它领域:加工时需要高粘力胶带贴 覆,加工后需要将胶带揭离且无残胶。

物理特性						
-		-	附注			
胶带厚度/(μm)		110±5	无离型膜			
基材		Po/100	材质/厚度(μm)			
外观	胶带	半透明 (目測)				
217%	离型膜	透明 (目測)	-			
粘色	粘合剂层		材质/厚度(μm)			
粘着力 (gf/25mm)	初始粘度	250-600	对钢板粘着力 -光照前 (180°剥离,放置 20min)			
	解胶后	<=20	对钢板粘着力 -光照后 (180°剥离,放置 20min)			
UV照射能量 (mj/cm2)	2	200-400	-			
保质期	银久洲。	原始包装,通常自银久洲发货日起 6 个月以内,具体产品请联系银久洲。 在0-40°C, < 80%的湿度的环境下,避光保存及运输。				

出货规格				
使用层厚度(μm)	宽度(mm)	长度(m)		
110	300&400	100		

注:可接受其它尺寸规格(宽度、额外长度),请联系银久洲。

使用说明

粘结强度取决于粘接物体表面的胶量,作业时 稳固的压力能够提高粘合剂的接触性能及粘结 强度。

为了获得最佳粘力,粘接表面必须要干净,干燥及均匀平整。典型清洁溶剂为酒精或乙酸乙酯。处理溶剂时使用适当的措施。

理想应用温度范围为21℃-38℃(70°F-100°F)初始的使用胶粘带粘贴表面时,不建议在10°C(50°F)以下进行。

运输及使用过程中注意避免光照导致产品失效。

联络方式

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Technical Data Sheet

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UV8110-PO10WF

UV tape

Introduction

UV8110-PO10WF is a UV adhesion-reducing protective film with a layer thickness of 110 µm, PO as the substrate, and coated with acrylic adhesive.

Product Features

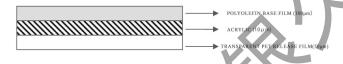
The viscosity is extremely high before UV irradiation, and the viscosity decreases sharply after UV irradiation, which can be easily peeled off without trace;

No glue residue and no pollution during use;

Excellent stickiness before UV, good protection and fixing effect;

product structure

UV tape consists of three parts from release film, acrylic adhesive and base film.



product application

It is suitable for the protection of electronic components, wafers, glass, ceramics, lenses, and chip positioning processes in the semiconductor industry.

Semiconductor: Dicing of various types of package (BGA/QFN/DFN), wafer sawing and grinding.

Optoelectronic: Slotting, dicing and pickling of coated glass and ordinary glass.

Others: Process in which work piece should be covered when machining and uncovered after that without adhesive residue.

Physical characteristics					
-			-	Remark	
Tape thickness (μm)			110±5	Without release film	
Base film		Polyolefin/100	Material / Thickness (μm)		
Appearance	Таре		Translucent		
			(eyeballing)		
	release film		Opaque	-	
			(eyeballing)		
Adhesive layer		Acrylic/10	Material / Thickness (μm)		
		Before	250-600	Adhesion to steel plates-before UV	
Adhesion (gf/25mm)		UV	250-600	(180° stripping, 20 minutes)	
		After	<=20	Adhesion to steel plates-after UV	
		UV		(180° stripping, 20 minutes)	
UV irradiation energy (mj/cm2)			200-400	-	
			200 100		
		Original packaging, usually within 6 months from the date of			
shelf life		shipment, please contact us for specific products.			
		Light avoidance and transport in 0-40°C, < 80% humidity.			

Shipping Specifications					
Use layer thickness(µm)	width(mm)	length(m)			
110	300&400	100			

Note: Other dimensions (width, extra length) are acceptable, please contact

Instructions for use

The bond strength depends on the amount of glue on the surface of the bonded object, and a firm pressure during operation can improve the contact performance and bond strength of the adhesive.

For optimum adhesion, the bonding surface must be clean, dry and evenly level. Typical cleaning solvents are alcohol or ethyl acetate. Use proper precautions

The ideal application temperature range is 21°C-38° C (70°F-100°F). When initially using adhesive tape to paste the surface, it is not recommended to use it below 10°C (50°F).

During transportation and use, pay attention to avoid light causing product failure.

contact method

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